

ABSTRACT

In a manufacturing process of electronic components which are composed of conductive patterns laminated with insulating layers provided therebetween, conductive pattern layers having conductive patterns 4, 5, 7, and 8 formed at intervals therebetween along layer surfaces and insulating layers 10 to 13 are alternately laminated to each other. As described above, a laminate is formed in which electronic components 1 are collectively formed by lamination of the conductive patterns 4, 5, 7, and 8. Subsequently, the laminate is pressed by applying a force thereto in the lamination direction, followed by cutting of the laminate along cutting lines provided along boundaries between the electronic components 1, so that the electronic components 1 are separated from each other. In a cutting-removal region Z of a mother substrate from which the electronic components 1 are separated from each other by cutting, removal dummy patterns 18 having a size which can be placed within the above region are formed. In the electronic component 1, floating dummy patterns 15 which are not electrically connected to the conductive patterns 4, 5, 7, and 8 are formed at intervals from the cutting-removal region Z.